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Description

The 74LVC2G04 is a dual inverter gate with standard push-pull outputs. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

The gate performs the positive Boolean function:

$$Y = \overline{A}$$

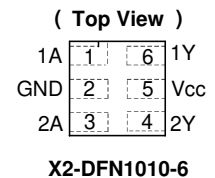
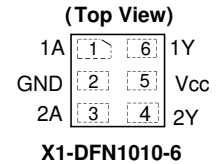
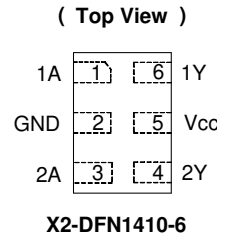
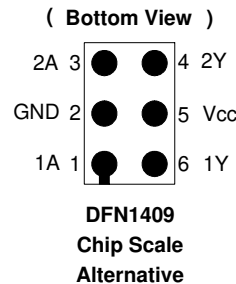
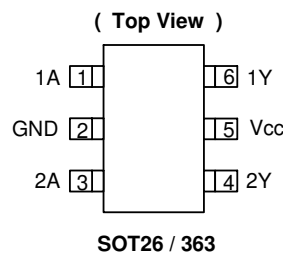
Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- $\pm 24\text{mA}$ Output Drive at 3.0V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115)
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- DFN1409 package designed as a direct replacement for chip scale packaging.
- Range of Package Options SOT26, SOT363, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, and X2-DFN1410-6
- Leadless Packages Named per JESD30E
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

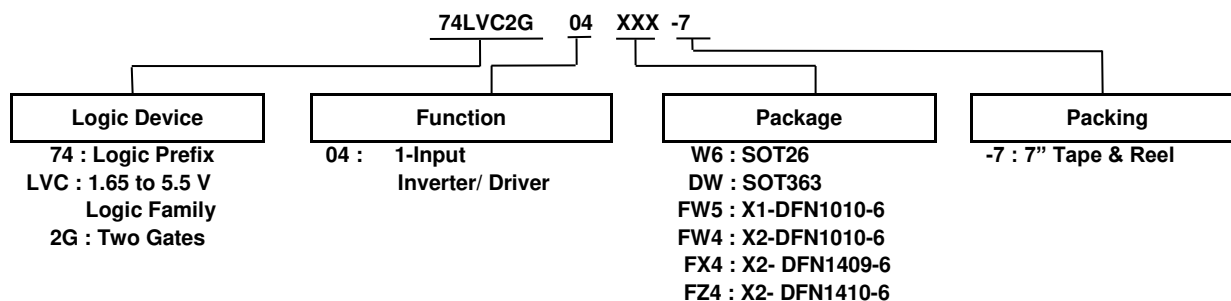
Pin Assignment



Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
 - PCs, Networking, Notebooks, Netbooks, Tablets
 - Computer Peripherals, Hard Drives, SSD, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Ordering Information



Device	Package Code	Package (Note 4)	Package Size	7" Tape and Reel (Note 5)	
				Quantity	Part Number Suffix
74LVC2G04W6-7	W6	SOT26	2.8mm X 2.2 mm X 1.1mm 0.95 mm lead pitch	3,000/Tape & Reel	-7
74LVC2G04DW-7	DW	SOT363	2.0mm X 2.0mm X 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74LVC2G04FW5-7	FW5	X1-DFN1010-6	1.0mm X 1.0mm X 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC2G04FW4-7	FW4	X2-DFN1010-6	1.0mm X 1.0mm X 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC2G04FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm X 0.9mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74LVC2G04FZ4-7	FZ4	X2-DFN1410-6	1.4mm X 1.0mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

Notes:

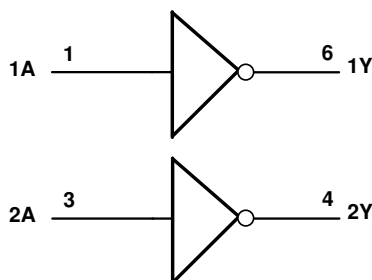
4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

5. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Pin.	Function
1A	1	Data Input
GND	2	Ground
2A	3	Data Input
2Y	4	Data Output
V _{CC}	5	Supply Voltage
1Y	6	Data Output

Logic Diagram



Function Table

Inputs	Output
A	Y
H	L
L	H

Absolute Maximum Ratings (Notes 6 & 7) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +6.5	V
V _I	Input Voltage Range	-0.5 to +6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to +6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current V _O < 0	-50	mA
I _O	Continuous Output Current	-50	mA
	Continuous Current Through V _{DD} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

- Note 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- Note 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V _{IH}	High-Level Input Voltage	V _{CC} = 1.65V to 1.95V	0.65 X V _{CC}	—	V
		V _{CC} = 2.3V to 2.7V	1.7	—	
		V _{CC} = 3V to 3.6V	2	—	
		V _{CC} = 4.5V to 5.5 V	0.7 X V _{CC}	—	
V _{IL}	Low-Level Input Voltage	V _{CC} = 1.65V to 1.95V	—	0.35 X V _{CC}	V
		V _{CC} = 2.3V to 2.7V	—	0.7	
		V _{CC} = 3V to 3.6V	—	0.8	
		V _{CC} = 4.5V to 5.5V	—	0.3 X V _{CC}	
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 3V	—	-16	
			—	-24	
		V _{CC} = 4.5V	—	-32	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 3V	—	16	
			—	24	
		V _{CC} = 4.5V	—	32	
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 1.8V ± 0.15 V, 2.5V ± 0.2V	—	20	ns/V
		V _{CC} = 3.3V ± 0.3V	—	10	
		V _{CC} = 5V ± 0.5V	—	5	
T _A	Operating Free-Air Temperature	—	-40	125	°C

Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	-40°C to +85°C		-40°C to +125°C		Unit
				Min	Max	Min	Max	
V _{OH}	High-Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	V _{CC} - 0.1	—	V
		I _{OH} = -4mA	1.65V	1.2	—	0.95	—	
		I _{OH} = -8mA	2.3V	1.9	—	1.7	—	
		I _{OH} = -16mA	3V	2.4	—	1.9	—	
		I _{OH} = -24mA		2.3	—	2.0	—	
		I _{OH} = -32mA	4.5V	3.8	—	3.4	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	0.1	—	0.1	V
		I _{OL} = 4mA	1.65V	—	0.45	—	0.70	
		I _{OL} = 8mA	2.3V	—	0.3	—	0.45	
		I _{OL} = 16mA	3V	—	0.4	—	0.60	
		I _{OL} = 24mA		—	0.55	—	0.80	
		I _{OL} = 32mA	4.5V	—	0.55	—	0.80	
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	—	± 5	—	± 20	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	± 10	—	± 20	μA
I _{CC}	Supply Current	V _I = 5.5V or GND I _O = 0	1.65V to 5.5V	—	10	—	40	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} -0.6V	3V to 5.5V	—	500	—	5000	μA

Package Characteristics (All typical values are at V_{CC} = 3.3V, T_A = +25°C.)

Symbol	Parameter	Package	Conditions	Min	Typ	Max	Unit
C _I	Input Capacitance	Typical of all packages	V _{CC} = 3.3V V _I = V _{CC} or GND	—	3.5	—	pF
θ _{JA}	Thermal Resistance Junction-to-Ambient	SOT26	(Note 9)	—	204	—	°C/W
		SOT363		—	371	—	
		X2-DFN1410-6		—	430	—	
		X2-DFN1409-6		—	450	—	
		X1-DFN1010-6		—	495	—	
		X2-DFN1010-6		—	510	—	
θ _{JC}	Thermal Resistance Junction-to-Case	SOT26	(Note 9)	—	52	—	°C/W
		SOT363		—	143	—	
		X2-DFN1410-6		—	190	—	
		X2-DFN1409-6		—	225	—	
		X1-DFN1010-6		—	245	—	
		X2-DFN1010-6		—	250	—	

Note: 9. Test condition for all packages: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

Switching Characteristics

T_A = -40°C to +85°C, C_L = 30 or 50pF (See Figure 1)

Parameter	From (Input)	TO (OUTPUT)	V _{CC} = 1.8V ± 0.15V		V _{CC} = 2.5V ± 0.2V		V _{CC} = 3.3V ± 0.3V		V _{CC} = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A	Y	0.5	8.0	1.0	4.4	0.5	4.1	0.5	3.2	ns

T_A = -40°C to +125°C, C_L = 30 or 50pF (See Figure 1)

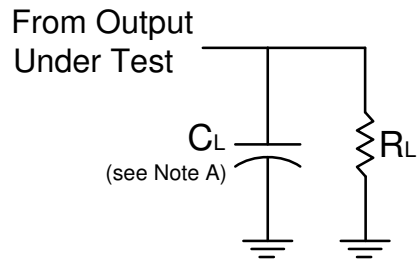
Parameter	From (Input)	TO (OUTPUT)	V _{CC} = 1.8V ± 0.15V		V _{CC} = 2.5V ± 0.2V		V _{CC} = 3.3V ± 0.3V		V _{CC} = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A	Y	0.5	9.5	0.5	5.4	0.5	5.5	0.5	3.8	ns

Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter		Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
			Typ	Typ	Typ	Typ	
C_{pd}	Power Dissipation Capacitance	$f = 10\text{MHz}$	17	19	20	21	pF

Parameter Measurement Information



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.8\text{V} \pm 0.15\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	30 pF	1 k Ω
$2.5\text{V} \pm 0.2\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	30 pF	500 Ω
$3.3\text{V} \pm 0.3\text{V}$	3V	$\leq 2.5\text{ns}$	1.5 V	50 pF	500 Ω
$5\text{V} \pm 0.5\text{V}$	V_{CC}	$\leq 2.5\text{ns}$	$V_{CC}/2$	50 pF	500 Ω

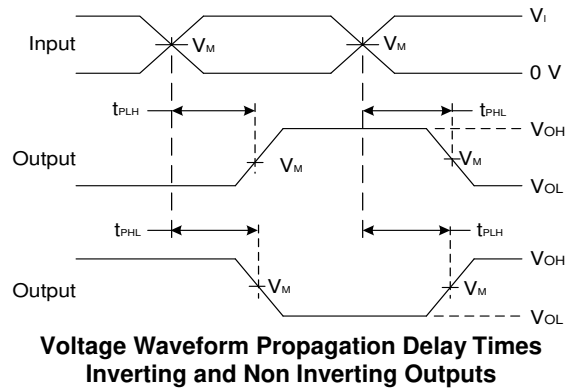
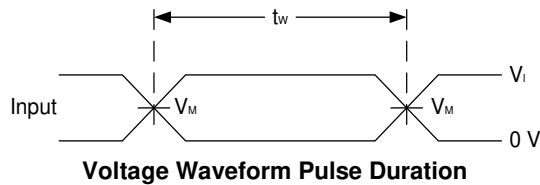
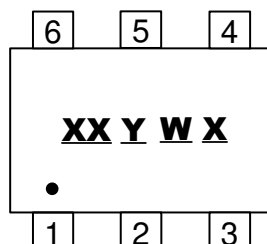


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10\text{ MHz}$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Marking Information

(1) SOT26, SOT363

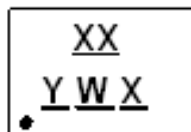


XX : Identification code
Y : Year 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC2G04W6-7	SOT26	Z2
74LVC2G04DW-7	SOT363	Z2

(2) X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

(Top View)

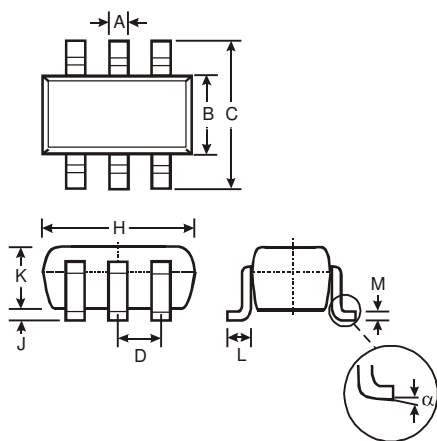


XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal code

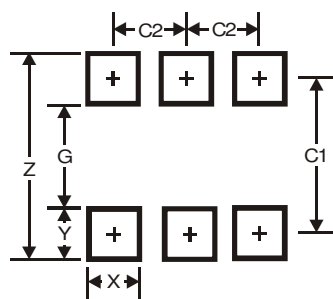
Part Number	Package	Identification Code
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74LVC2G04FW5-7	X1-DFN1010-6	W2
74LVC2G04FX4-7	X2-DFN1409-6	X2
74LVC2G04FZ4-7	X2-DFN1410-6	Z2

SOT26 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



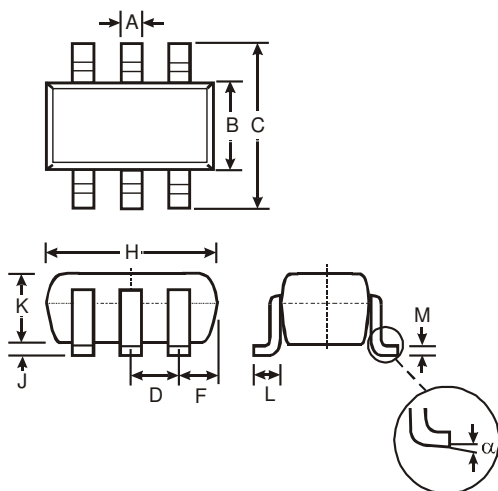
SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			



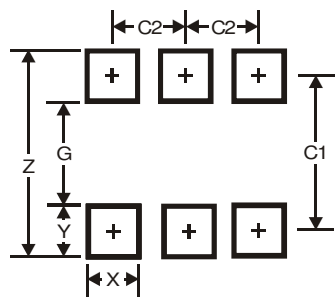
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

SOT363 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



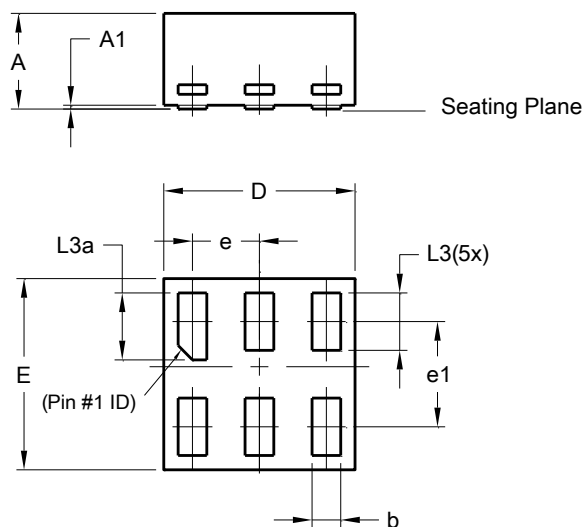
SOT363			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
All Dimensions in mm			



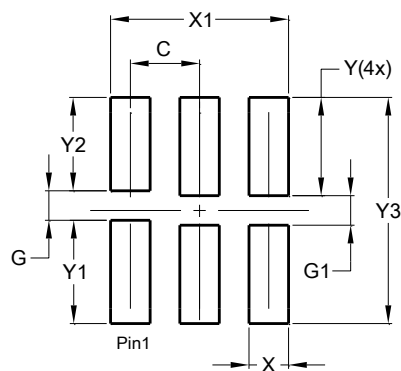
Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



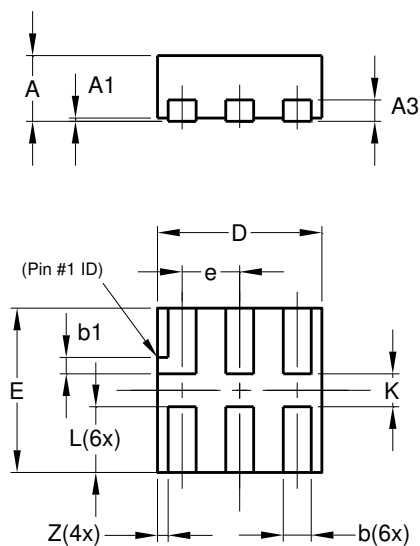
X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			



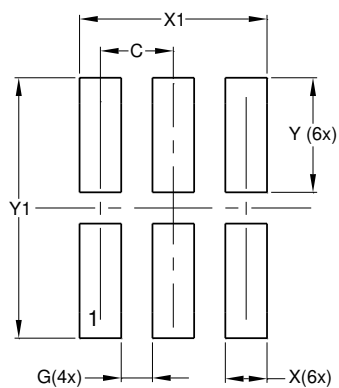
Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



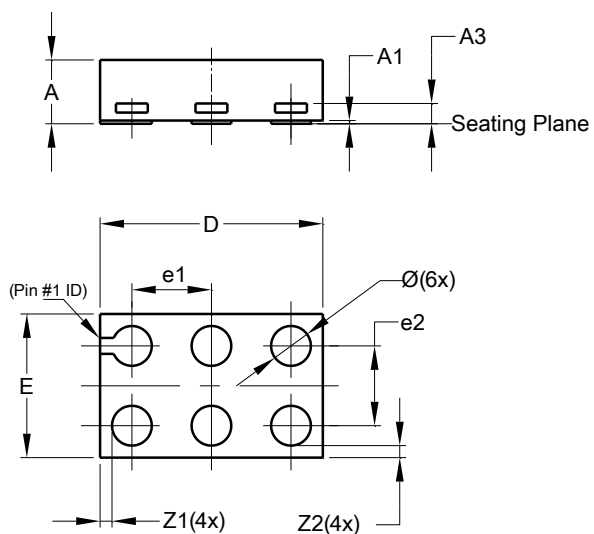
X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			



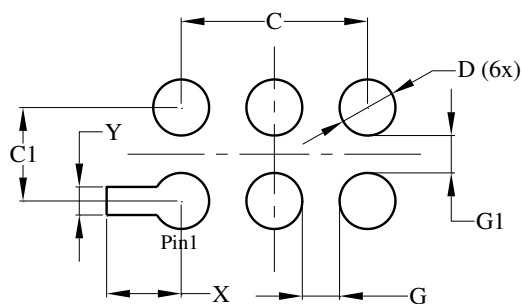
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



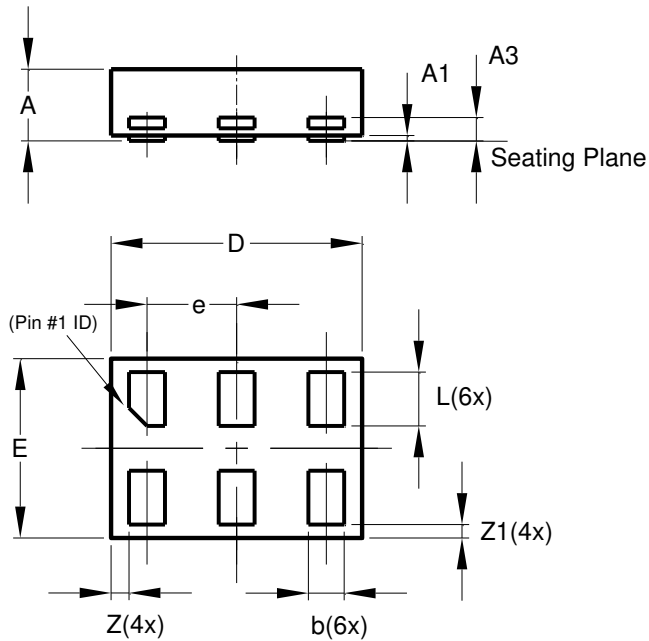
X2-DFN1409-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0	0.05	0.02
A3	—	—	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	—	—	0.50
e2	—	—	0.50
Z1	—	—	0.075
Z2	—	—	0.075
All Dimensions in mm			



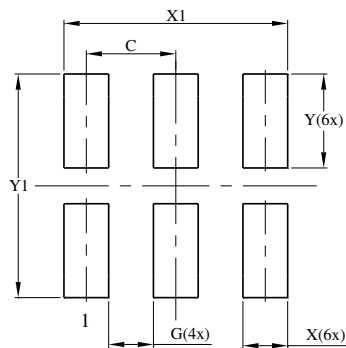
Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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